

CLAIMS

What is claimed is:

1. An optoelectronic hermetic package, comprising:
a frame defining a hermetic boundary; and
an electrical feedthrough assembly on the frame 1) providing electrical connections
between signal wire bond areas within the hermetic boundary and electrical
contact areas outside the hermetic boundary and 2) ground wire bond areas
within the hermetic boundary to each other.
2. A package as claimed in claim 1, further comprising an array of leads extending
from electrical contact areas away from the frame.
3. A package as claimed in claim 2, wherein the leads extend laterally relative to the
frame.
4. A package as claimed in claim 2, wherein the pins extend vertically relative to the
frame.
5. A package as claimed in claim 1, wherein at least some of the ground wire bond
areas are located between two of the signal wire bond areas on the feedthrough
assembly.
6. A package as claimed in claim 1, wherein the ground wire bond areas are
interdigitated with signal wire bond areas.
7. A package as claimed in claim 1, further comprising conductive plugs extending
between a top of the feedthrough assembly and the frame, the ground wire bond areas
being located on a top of the conductive plugs.

8. A package as claimed in claim 1, wherein the assembly provides electrical connections between the ground wire bond areas and the frame.

9. A package as claimed in claim 1, further comprising conductive plugs extending between a top of the feedthrough assembly and a bus through the assembly, the ground wire bond areas being located on a top of the conductive plugs.

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